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FOR PRODUCING COPPER/CERAMIC
BONDED BODY, AND METHOD FOR
PRODUCING INSULATING CIRCUIT
BOARD****Publication Classification**

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(71) Applicant: **mitsubishi materials
CORPORATION**, Tokyo (JP)(72) Inventor: **Nobuyuki Terasaki**, Saitama-shi (JP)(73) Assignee: **mitsubishi materials
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(57) **ABSTRACT**

This copper/ceramic bonded body includes: a copper member made of copper or a copper alloy; and a ceramic member made of nitrogen-containing ceramics, the copper member and the ceramic member are bonded to each other, in which, between the copper member and the ceramic member, an active metal nitride layer containing nitrides of one or more active metals selected from Ti, Zr, Nb, and Hf is formed on a ceramic member side, and a Mg solid solution layer in which Mg is solid-dissolved in a Cu matrix is formed between the active metal nitride layer and the copper member, and Cu-containing particles composed of either one or both of Cu particles and compound particles of Cu and the active metal are dispersed in an interior of the active metal nitride layer.

